

**CONTINUATION-IN-PART PATENT APPLICATION TRANSMITTAL**  
(37 C.F.R. § 1.53(b))

Attorney Docket No.: BDG024

Inventor: Chuen Rong Leu of Hsinchu, Taiwan  
Charles W.C. Lin of Singapore

Title: SEMICONDUCTOR CHIP ASSEMBLY WITH EMBEDDED METAL PILLAR

Prior Group Art Unit: 2818  
Prior Examiner: R. Berry

**Mail Stop Patent Application**  
**Commissioner for Patents**  
P.O. Box 1450  
Alexandria, VA 22313-1450

This patent application is a CONTINUATION-IN-PART application of pending prior U.S. Application Serial No. 10/235,331 filed September 5, 2002, which is a divisional application of U.S. Application Serial No. 09/939,140 filed August 24, 2001, which is a continuation-in-part application U.S. Application Serial No. 09/878,626, filed June 11, 2001, which is a continuation-in-part application of U.S. Application Serial No. 09/687,619, filed October 13, 2000.

This patent application also claims the benefit of U.S. Provisional Application Serial No. 60/509,299 filed October 7, 2003, and U.S. Provisional Application Serial No. 60/507,145 filed September 30, 2003.

Enclosed for filing with the above-identified utility patent application, please find the following:

1.     ☒     Application, consisting of  
                                Specification (66 pages)  
                                Claims (17 pages)  
                                Abstract (1 page)  
                                Drawings (36 sheets) (informal)
2.     ☒     Declaration
3.     ☒     Assignment Papers (*Cover Sheet & Assignment*)
4.     ☒     Power of Attorney
5.     ☒     Statement under 37 C.F.R. § 3.73(b) Establishing Right of Assignee to Take Action
6.     ☒     Information Disclosure Statement (IDS/PTO-1449)
7.     ☒     Statement Claiming Small Entity Status by Small Business Concern
8.     ☒     Request for Nonpublication of Application
9.     ☒     Return Postcard (MPEP 503) (*specifically itemized*)



**FEE CALCULATION:**

	(COL. 1) NO. FILED			(COL. 2) NO. EXTRA	SMALL ENTITY	
					RATE	FEE
BASIC FEE:						\$385
TOTAL CLAIMS:	100	-	20	80	X \$9 =	\$720
INDEP. CLAIMS:	6	-	3	3	X \$43 =	\$129
MULTIPLE DEPENDENT CLAIMS: 0					+\$140 =	\$0
TOTAL FILING FEE						\$1234

**OTHER INFORMATION:**

1. Charge the \$1234 to Deposit Account No. 502178/BDG024 and charge any underpayment or credit any overpayment to this Account.
2. The application is assigned to Bridge Semiconductor Corporation.
3. Correspondence Address:

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EXPRESS MAIL MAILING LABEL NUMBER: EU267708587US  
DATE OF DEPOSIT: NOVEMBER 17, 2003

ADDRESSEE: MAIL STOP PATENT APPLICATION  
COMMISSIONER FOR PATENTS  
P.O. BOX 1450  
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Respectfully submitted,

David M. Sigmond  
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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Chuen Rong Leu et al.  
Assignee: Bridge Semiconductor Corporation  
Title: SEMICONDUCTOR CHIP ASSEMBLY WITH EMBEDDED METAL PILLAR  
Serial No.: Unknown Filed: Herewith  
Examiner: Unknown Group Art Unit: Unknown  
Atty. Docket No.: BDG024

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COMMISSIONER FOR PATENTS  
P.O. Box 1450  
Alexandria, VA 22313-1450

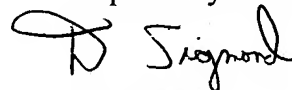
**REQUEST FOR NONPUBLICATION OF APPLICATION**

Applicant requests that the above-identified application not be published under 35 U.S.C. § 122(b).

Applicant certifies that the invention disclosed in this application has not been and will not be the subject of an application filed in another country, or under a multilateral international agreement, that requires publication at eighteen months after filing.

This request is being submitted with this application on filing.

Respectfully submitted,



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